August 25, 2026

Qnity Expands AI-Driven Advanced Packaging Capabilities with End-to-End Process Solutions

Integrated portfolio spans metallization, bumping, dielectric and fine-line patterning for 2.5D, 3D and panel-level architectures

WILMINGTON, Del.--(BUSINESS WIRE)-- Qnity Electronics, Inc. (“Qnity”) (NYSE: Q), a premier technology solutions leader across the semiconductor value chain, today introduced a scalable materials solution platform that brings together metallization, bumping, dielectric, and fine-line patterning technologies to enable next-generation high-density and 3D integrated semiconductor systems. The platform enables AI-driven advanced packaging, where finer interconnects, higher density, and improved manufacturing yields determine whether a design can successfully scale.

"Customers are looking for system-level solutions, and that's where Qnity shines,” said Chuck Xu, President, Interconnect Solutions, Qnity. “As AI, chiplets, high-bandwidth memory, 3D stacking, and heterogeneous integration drive a shift from 2D designs to increasingly complex vertical architectures, semiconductor manufacturers are facing new levels of integration complexity, creating demand for integrated solutions spanning advanced packaging and thermal management. Our teams serve as a design partner with end-to-end process development and engineering capabilities that help customers solve the integration complexity layer-to-layer, chip-to-chip, and scale new designs with confidence."

Advanced packaging platforms such as Chip-on-Wafer-on-Substrate (CoWoS), Embedded Multi-die Interconnect Bridge (EMIB), and high-bandwidth memory (HBM) require precise plating height control and superior coplanarity. Qnity's integrated portfolio supports tin-silver (SnAg) micro-bumps, copper-to-copper (Cu-Cu) direct and hybrid bonding, and high-resolution dielectric and patterning processes, enabling 2 µm line/space metallization with tight critical dimension (CD) control and low defectivity.

Qnity will detail the platform in a presentation by Jason Chuang, Packaging Polymer Segment Director, Advanced Circuit & Packaging, at the Heterogeneous Integration Global Summit during SEMICON Taiwan 2026 on Sept. 1. Attendees are invited to meet with Qnity experts to discuss the trends shaping the future of advanced semiconductor packaging.

Key solutions include:

Intervia™ CB1000+ / CB3000 copper. Designed for enhanced within-die (WID) uniformity, a wide operating window, strong total indicated runout (TIR) control, and low-impurity copper deposition.

Solderon™ TS8000 series solder. A SnAg micro-bump plating solution for HBM applications that delivers excellent coplanarity for mixed-pitch and fine-pitch micro-bumps

while supporting both soluble and insoluble electrode plating applications.

Riston® WBR5000 dry film photoresist. A next-generation thick dry film photoresist for 2.5D advanced packaging, enabling high-aspect-ratio copper pillar plating and fine-feature lithography with 200–320 µm film thickness.

Cyclotene™ dry film photo-imageable dielectric. Designed for fan-out panel-level packaging and advanced substrate. It delivers excellent coplanarity and achieves target thickness in a single step. For glass core substrates, it enables effective filling of through-glass vias (TGVs) and has demonstrated robust reliability performance.

To view the full agenda, learn more about Qnity's activities at SEMICON Taiwan, and request a meeting, visitors are encouraged to explore Qnity's virtual booth and visit us at booth S7930 in the Materials Pavilion at TaiNEX 2.

Learn more about Qnity's solutions for advanced packaging at our Advanced Packaging Innovation Hub.

About Qnity
Qnity is a premier technology provider across the semiconductor value chain, empowering AI, high performance computing, and advanced connectivity. From groundbreaking solutions for semiconductor chip manufacturing, to enabling high-speed transmission within complex electronic systems, our high-performance materials and integration expertise make tomorrow's technologies possible. More information about the company, its businesses and solutions can be found at www.qnityelectronics.com.

Qnity™, the Qnity Node Logo, and all products, unless otherwise noted, denoted with ™ or ® are trademarks, trade names or registered trademarks of affiliates of Qnity Electronics, Inc.

View source version on businesswire.com:
https://www.businesswire.com/news/home/20260825628988/en/

Qnity Media Contact

Ashley Boucher
ashley.boucher@qnityelectronics.com

Winnie Chou
winnie.chou@qnityelectronics.com
+886922203452

Source: Qnity Electronics, Inc.